

\ Page 3, line 21, change "alternative" to --alternatively-- and after "device" insert --which--.

\ Page 3, line 24, change "wining" to --wiring--.

\ Page 3, line 26, change "confronting" to --conforming--.

\ Page 4, line 1, insert --which-- before "comprises" and insert ")" after "bonding".

\ Page 4, line 6, change "confronting" to --conforming--.

\ Page 4, line 10, after "device" insert --which--.

\ Page 4, line 14, change "confronting" to --conforming--.

\ Page 6, line 10, change "Bonding" to --bonding--.

\ Page 7, line 15, change "embodiment" to --embodiments--.

\ Page 8, line 25, change "According" to --Accordingly--.

IN THE CLAIMS:

Please amend claims 1, 4, 6, 11 and 16 as follows:

- A'
1. (Amended) A semiconductor device [comprises] comprising:
a wiring substrate having a predetermined pattern of wiring formed on one surface;
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a semiconductor chip disposed on the other surface of said [wining] wiring substrate and having two or more chip electrodes in a common wiring layer;
said wiring substrate having a number of through-holes; [and]

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con d.

a number of bumps formed respectively in said through-holes in [confronting]
conforming relationship with said two or more chip electrodes and electrically
connecting said wiring with said two or more chip electrodes[.]; and
an external bump pad electrically connected through said common wiring layer
to said two or more chip electrodes.

A²

4. (Amended) A semiconductor device according to claim 1, wherein said
chip electrodes are arranged parallel to an edge of said semiconductor [chip] chip and
said wiring has an end width larger than an inter-electrode distance between said chip
electrodes.

A³

6. (Amended) A semiconductor device [comprises] comprising:
a wiring substrate having a predetermined pattern of wiring formed on one
surface;
a semiconductor chip disposed on said one surface of said [wiring] wiring
substrate and having two or more chip electrodes in a common wiring layer; [and]
a number of bumps disposed on said wiring respectively in [confronting]
conforming relationship with said two or more chip electrodes and electrically
connecting said wiring with said two or more chip electrodes[.]; and
an external bump pad electrically ^{connected} converted through said common wiring layer
to said two or more chip electrodes.

B

11. (Amended) A semiconductor device [comprises] comprising:

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a TAB (tape automated bonding) tape having a predetermined pattern of wiring formed on one surface;

a semiconductor chip disposed on the other surface of said TAB tape and having two or more chip electrodes in a common wiring layer;

said TAB tape having a number of through-holes; [and]

a number of bumps formed respectively in said through-holes in [confronting] conforming relationship with said two or more chip electrodes and electrically connecting said wiring with said two or more chip electrodes[.]; and

an external bump pad electrically connected through said common wiring layer to said two or more chip electrodes.

A5

16. (Amended) A semiconductor device [comprises] comprising:

a TAB tape having a predetermined pattern of wiring formed on one surface;

a semiconductor chip disposed on said one surface of said TAB tape and having two or more chip electrodes in a common wiring layer; [and]

a number of bumps disposed on said wiring respectively in [confronting] conforming relationship with said two or more chip electrodes and electrically connecting said wiring with said two or more chip electrodes[.]; and

an external bump pad electrically connected through said common wiring layer to said two or more chip electrodes.

IN THE ABSTRACT:

\ Page 14, line 5, change "tow" to --two--.